



Intel® Smart Sound Technology Driver

Release Notes: Jasper Lake Intel SST Release

October 2020

Revision 0.3

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Revision History

Revision Version	Revision History	Revision Date
0.1	Intel® SST Jasper Lake Release 7318	July 2020
0.2	Intel® SST Jasper Lake Release 7429	July 2020
0.3	Intel® SST Jasper Lake Release 4576	Oct 2020

1 Introduction

1.1 Scope of Document

This document provides release information about the Intel® Smart Sound Technology (Intel® SST) Driver. It covers Release Kit summary, Important Notes, Known and Closed Issues.

This document is intended for OEMs and ODMs that are validating the Intel® Smart Sound Technology Driver on Jasper Lake (JSL) platforms with Intel Audio DSP integrated

1.2 System Requirements

Intel® Smart Sound Technology Driver supports the following Intel CPU/Chipset:

- Jasper Lake Processors

Platform Support:

- Jasper Lake processor-based platforms with Intel Audio DSP integrated

Operating Systems support:

- Microsoft Windows* 10 64-bit

1.3 Acronyms and Terminology

Term	Description
ACPI	Advanced Configuration and Power Interface
BIOS	Basis Input/output System
BT	Bluetooth

DMIC	Digital Microphone
DSP	Digital Signal Processor
EA	Enrollment Application
FDK	Firmware Development Kit
FW	Firmware
HDA or HD-Audio	High Definition Audio
HFP	Hands-Free Profile
IHV	Independent Hardware Vendor
ISV	Independent Software Vendor
Intel® SST	Intel® Smart Sound Technology
IPR	Ingredient Planned Release
JSL	Jasper Lake
LP	Low power
MCP	Multi-Chip Package
MCPS	Million Clocks Per Second
MCS	Modern Connected Standby Platform
Non-MCS	Non-Modern Connected Standby Platform
OED	Offload Engine Driver
OS	Operating System
PCH	Platforms Controller Hub
RVP	Reference Validation Platform
SUT	System under test
TBD	To be determined
ULT	Ultra-Thin
WOV	Wake on Voice.
PC	Production Candidate

PV	Production Version
PR	Planned Release
TH	Threshold
RS	Redstone
MR	Maintenance Release



2 *Release Kit Summary*

2.1 Release Kit

Kit Name: Intel® Smart Sound Technology Driver Jasper Lake Release

Supported OS: Windows* 10 64-bit

Version: 10.26.00.4576

2.2 Kit Contents

The contents of this release kit include:

- Drivers
 - DSP Firmware
 - Topology
 - WOV Artifacts
 - IntcAudiobus – Intel SST Audio Bus Driver for HD-A I/F
 - IntcOED – Intel SST Offload Engine Driver
 - Detection Verification Driver
 - Intel® DMIC driver
 - Intel® Bluetooth Audio Driver
 - Intel® SST I2S Driver
- Module Version
 - Intel WOV version 2.0.668.20_368
 - Intel Audio Service version 01.00.1520.00
- Apps
 - Intel® Audio Service: Part of Intel SST OED Installation.
 - Intel WOV Client Application
 - Intel MVA Extension
- Intel® Smart Sound Technology Driver – Release Notes

3 *Intel® SST Release Details*

3.1 Intel® Smart Sound Technology Collaterals

Please refer to following Intel® SST collaterals for Intel® SST bring-up, validation and debug guidance.

Doc Number & Location	Doc Number & Location
Intel® Smart Sound Technology Driver - Bring-Up Guide	Included in every SST release package
Intel® Smart Sound Technology Customer - Validation and Debug Guide	Intel CDI Doc #575270

3.2 Platform Best Known Configuration

Please refer to Rocket Lake BKC Release.

3.3 Focused Testing Area

Please refer to the Intel® Smart Sound Technology Validation and Debug Guide on Intel® CDI (Document # 575270) for the test cases to test the following Intel® SST features.

For Desktop Processors:

- HD-Audio Playback
- HD-Audio Capture
- Digital Microphone Capture

For Mobile Processors:

- HD-Audio Playback
- HD-Audio Capture
- Digital Microphone Capture
- Intel® Wake on Voice - Contact Intel FAE or Intel® SST AE for more details.
- Post-processing - Contact Intel FAE or Intel® SST AE for more details.
- Pre-processing - Contact Intel FAE or Intel® SST AE for more details.



4 Intel® SST Release Highlights

Intel® SST Features		Highlights
Intel® Wake on Voice	WOVSetupApplication	Intel® WakeOnVoice Setup Application for Intel WOV IP supports: ○ Predefined Key Phrase on Win 10: Supported on Intel® WOV. Keyphrase is "Hello Computer".
	WOVClientApplication	○ User Defined Key Phrase: Supported on Intel® WOV. ○ Speaker Verification: Supported on Intel® WoV Note: WOVClientApplication for testing WOV is included in the release package inside the "Apps" folder.
Intel® Audio Service	Intel® Audio Service	Intel® Audio Service installer is provided for to support Intel WOV via Intel Speech Pin
Intel® SST Post-Processing		Post processing IP ISVs will integrate their audio IP FW modules using the Intel audio FDK tool and provide their FW to the IHV's for final audio driver and FW integration for OEM customer platforms.
Intel® SST Pre-Processing	Intel Preprocessing IP	Intel Preprocessing FW is included. Note: Pre-processing IP ISVs will integrate their audio IP FW modules using the Intel audio FDK tool and provide their FW to the IHV's for final audio driver and FW integration for OEM customer platforms.
HD Audio Interface	NA	HD Audio interface support has been implemented and included in CFL Intel® SST Release. Disclaimer: To test HD-A interface, a codec driver from audio codec vendor is required. Please contact your codec vendor to obtain the driver supporting this feature.
I2S Interface	NA	I2S Interface support has been implemented and included in the Release. Disclaimer: To test I2S interface, a codec driver from audio codec vendor is required. Please contact your codec vendor to obtain the driver supporting this feature.

SoundWire Interface	NA	SoundWire interface support has been implemented and included in CFL Intel® SST Release. Disclaimer: To test SoundWire interface, a sound wire driver from SoundWire device vendor is required. Please contact your sound wire device vendor to obtain the driver supporting this feature.
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5 *Important Notes:*

This build is not designed to work with WOV.

There is no SRAM sharing functionality.

Please disable WOV functionality in BIOS before driver installation.

6 *Known Issues*

Issue #	Description
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7 *Closed Issues*

Sighting	Title	Fixed version
18013176317	PV bit is not working on revenue parts	4576